Electronic Patent Application Fee Transmittal							
Application Number:	10539735						
Filing Date:	20-Jun-2005						
Title of Invention:	SURFACE-MOUNTED MICROWAVE PACKAGE AND CORRESPONDING MOUNTING WITH A MULTILAYER CIRCUIT						
First Named Inventor/Applicant Name:	Phillippe Kertesz						
Filer:	Kenneth M. Berner/Candace Chambliss						
Attorney Docket Number:	4590-426						
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
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Claims:							
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